

HAT2026R

Silicon N Channel Power MOS FET High Speed Power Switching

REJ03G1161-0500

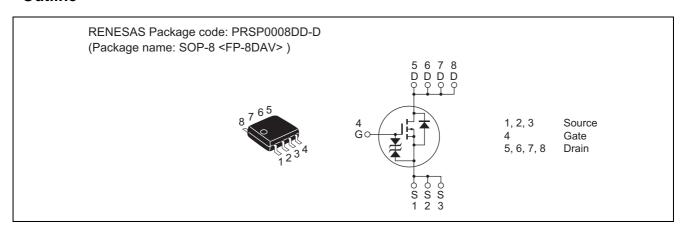
(Previous: ADE-208-523C)

Rev.5.00 Sep 07, 2005

Features

- Low on-resistance
- Capable of 2.5 V gate drive
- Low drive current
- High density mounting

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit	
Drain to source voltage	V _{DSS}	20	V	
Gate to source voltage	V _{GSS}	±12	V	
Drain current	I _D	11	Α	
Drain peak current	I _{D (pulse)} Note 1	88	Α	
Body-drain diode reverse drain current	I _{DR}	11	Α	
Channel dissipation	Pch Note 2	2.5	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. When using the glass epoxy board (FR4 $40\times40\times1.6$ mm), PW ≤10 s

Electrical Characteristics

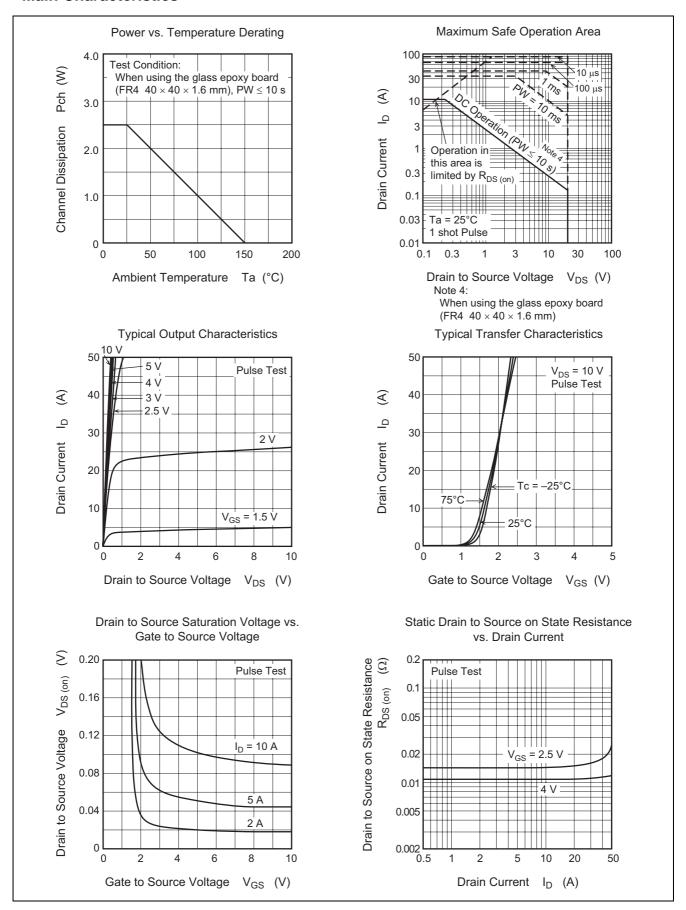
 $(Ta = 25^{\circ}C)$

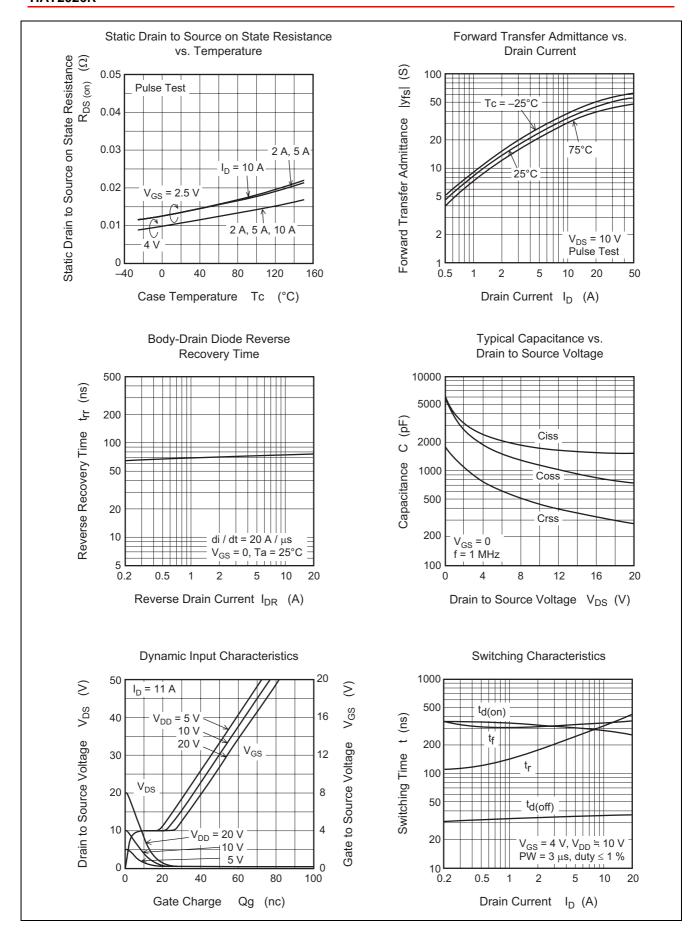
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR) DSS}	20	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR) GSS}	±12	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 20 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	0.4	_	1.4	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Static drain to source on state resistance	R _{DS (on)}	_	0.011	0.015	Ω	$I_D = 6 \text{ A}, V_{GS} = 4 \text{ V}^{\text{Note 3}}$
	R _{DS (on)}	_	0.014	0.021	Ω	$I_D = 6 \text{ A}, V_{GS} = 2.5 \text{ V}^{\text{Note 3}}$
Forward transfer admittance	y _{fs}	18	27	_	S	$I_D = 6 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note 3}}$
Input capacitance	Ciss	_	1760	_	pF	V _{DS} = 10 V
Output capacitance	Coss	_	1130	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	450	_	pF	f = 1 MHz
Turn-on delay time	t _{d (on)}	_	35	_	ns	$V_{GS} = 4 \text{ V}, I_D = 6 \text{ A},$
Rise time	t _r	_	275	_	ns	V _{DD} ≅ 10 V
Turn-off delay time	t _{d (off)}	_	300	_	ns	
Fall time	t _f	_	340	_	ns	
Body-drain diode forward voltage	V_{DF}	_	0.83	1.08	V	I _F = 11 A, V _{GS} = 0 Note 3
Body-drain diode reverse recovery time	t _{rr}	_	75	_	ns	I _F = 11 A, V _{GS} = 0
						$di_F/dt = 20 A/\mu s$

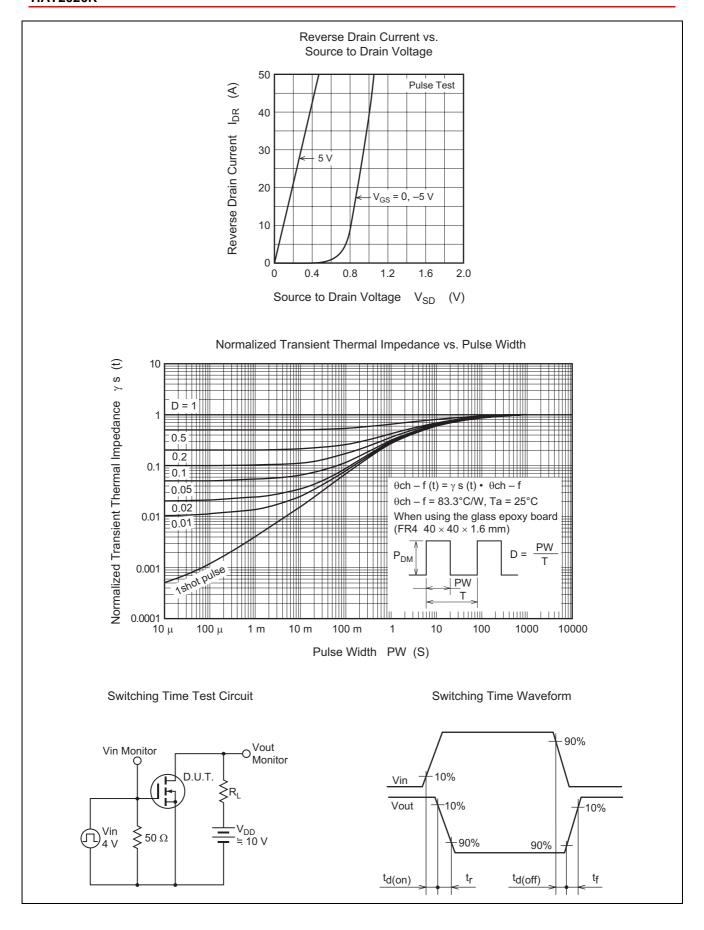
Note: 3. Pulse test

The specifications may be change without notice.

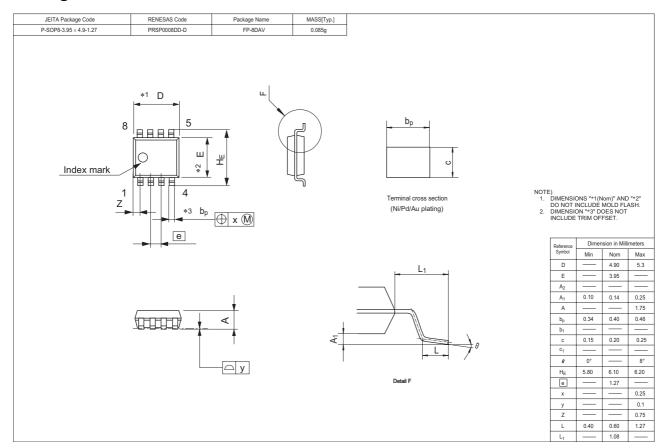
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT2026R-EL-E	2500 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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